

FORM PTO-1449
(REV. 7-80)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
500986.02 (30022/US)APPLICATION NO.
10/057,205

INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

APPLICANT(S)
Sion C. Quinlan et al.FILING DATE
January 25, 2002GROUP ART UNIT
2829

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
SBG	AA 6,021,499	02/01/00	Aleshi	713	300	
	AB					
	AC					
	AD					
	AE					
	AF					
	AG					
	AH					
	AI					
	AJ					

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
SBG	AK 00/45420	08/03/00	WO	—	—	X	
SBG	AL 0 801 468 A2	10/15/97	EP	—	—	X	
	AM						
	AN						
	AO						

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	AP	
	AQ	
	AR	

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Aut B. Bz

DATE CONSIDERED

12/4/03

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500986.02APPLICATION NO.
Not Yet Assigned**INFORMATION DISCLOSURE STATEMENT**

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APPLICANT(S)
Sion C. QUINLAN and Tim J. BALESFILING DATE
Concurrently herewithGROUP ART UNIT
28291-825 U.S. 10
10/05/2005
01/25/03**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
SBG	AA	5,975,958	11-02-99	Weidler	439	620	
SBG	AB	6,023,202	02-08-00	Hill	333	24	
SBG	AC	6,109,971	08-29-00	Vadlakonda	439	620	
SBG	AD	6,124,756	09-26-00	Yaklin et al.	327	564	
SBG	AE	6,147,542	11-14-00	Yaklin	327	344	
SBG	AF	6,249,171 B1	06-19-01	Yaklin et al.	327	382	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AG							

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

SBG	AH	Al-sarawi, Said F., "Wire Bonded Stacked Chips." Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node35," January 25, 2002, pp. 1-2
SBG	AI	Al-sarawi, Said F., "Blind Castellations Interconnection," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node44," January 25, 2002, p. 1
SBG	AJ	Al-sarawi, Said F., "Silicon Efficiency," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node20," January 25, 2002, pp. 1-2
SBG	AK	Al-sarawi, Said F., "Delay," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node22," January 25, 2002, p. 1

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A.D. Dg

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8/21/03


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INFORMATION DISCLOSURE STATEMENT <i>(Use several sheets if necessary)</i>		APPLICANT(S) Sion C. QUINLAN and Tim J. BALES	
		FILING DATE Concurrently herewith	GROUP PART UNIT 2 0 24

OTHER PRIOR ART *(Including Author, Title, Date, Pertinent Pages, Etc.)*

SBG	AL	Al-sarawi, Said F., "Noise," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node23 ," January 25, 2002, p. 1
SBG	AM	Al-sarawi, Said F., "Power Consumption," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node24 ," January 25, 2002, p. 1
SBG	AN	Al-sarawi, Said F., "Speed," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node25 ," January 25, 2002, p. 1
SBG	AO	Al-sarawi, Said F., "Interconnect Capacity," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node26 ," January 25, 2002, pp. 1-2
SBG	AP	Al-sarawi, Said F., "Interconnection Capacity Between Packaging Levels," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node27 ," January 25, 2002, p. 1
SBG	AQ	Al-sarawi, Said F., "Stacked Tape Carrier," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node30 ," January 25, 2002, p. 1
SBG	AR	Al-sarawi, Said F., "Solder Edge Conductors," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node31 ," January 25, 2002, pp. 1-2
SBG	AS	Al-sarawi, Said F., "Thin Film Conductors on Face-of-a-Cube," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node32 ," January 25, 2002, pp. 1-2
SBG	AT	Al-sarawi, Said F., "An Interconnection Substrate Soldered to the Cube Face," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node33 ," January 25, 2002, pp. 1-2

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INFORMATION DISCLOSURE STATEMENT <i>(Use several sheets if necessary)</i>		APPLICANT(S) Sion C. QUINLAN and Tim J. BALES	
		FILING DATE Concurrently herewith	GROUP ART UNIT 2829

OTHER PRIOR ART *(Including Author, Title, Date, Pertinent Pages, Etc.)*

SBG	AU	Al-sarawi, Said F., "Folded Flex Circuits," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node34 ," January 25, 2002, p. 1
SBG	AV	Al-sarawi, Said F., "Area Interconnection Between Stacked ICs," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node36 ," January 25, 2002, p. 1
SBG	AW	Al-sarawi, Said F., "Flip-chip Bonded Stacked Chips Without Spacers," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node37 ," January 25, 2002, p. 1
SBG	AX	Al-sarawi, Said F., "Flip-chip Bonded Stacked Chips With Spacers," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node38 ," January 25, 2002, p. 1
SBG	AY	Al-sarawi, Said F., "Microbridge Springs and Thermomigration Vias," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node39 ," January 25, 2002, p. 1
SBG	AZ	Agere Systems - About 1394, "1394 - The High-Speed Serial Interface for All the Right Reasons/1394 Driver Support," obtained from website http://www.agree.com/1394/about.html ," January 25, 2002, p. 1
SBG	BA	Press Release Tuesday October 17, 2000, "Lucent Technologies introduces low-power IEEE-1394A chip for high-speed connection between PCs and consumer electronic devices," obtained from website http://www.lucent.com/press/1000/001017.mea.html ," January 25, 2002, pp. 1-3
SBG	BB	1394 Trade Association: Technology, "1394 Technology," obtained from website http://www.1394ta.org/Technology/ ," January 25, 2002, p. 1
SBG	BC	1394 Trade Association: Technology, "An Introduction to the Instrument and Industrial Control Protocol," obtained at website http://www.1394ta.org/Download/Technology/iicpPaper2.pdf ," January 25, 2002, 6 pages
	BD	
	BE	

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8/21/03

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FORM PTO-144 (REV. 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 500986.02	APPLICATION NO. 10/057,205
INFORMATION DISCLOSURE STATEMENT <i>(Use several sheets if necessary)</i> COPY OF PAPERS ORIGINALLY FILED		APPLICANT(S) Sion C. QUINLAN and Tim J. BALES	
		FILING DATE January 25, 2002	GROUP ART UNIT 2812 2829

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	CLASS	NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
AA						TECHN.	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
AB						YES NO

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

SBG	AC	Apple Computer, Inc., "Firewire Technology Fact Sheet," obtained at website "http://a772.g.akamai.net/7/772/51/f7f756ae8e5bf0/www.apple.com/firewire/pdf/FireWireFS-b.pdf", March 13, 2002, pp. 1-4
SBG	AD	McMunn, Lee James, "The Physical Layer," obtained at website "http://www.awstevenson.demon.co.uk/SYSNOTES/physic.htm," March 12, 2002, pp. 1-2
SBG	AE	Willis, P. J., "Communication Protocols," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/chapter2_6.html," August 17, 2001, p. 1
SBG	AF	Willis, P. J., "The OSI Model," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/sections2_6_1.html," August 17, 2001, p. 1
SBG	AG	Willis, P. J., "Physical Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/subsection2_6_1_1.html," August 17, 2001, p. 1
SBG	AH	Willis, P. J., "Data Link Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/subsection2_6_1_2.html," August 17, 2001, p. 1
SBG	AI	Willis, P. J., "Network Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/subsection2_6_1_3.html," August 17, 2001, p. 1
SBG	AJ	Willis, P. J., "The Physical Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/section2_7_1.html," August 17, 2001, pp. 1-2
SBG	AK	Willis, P. J., "The Datalink Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/section2_7_2.html," August 17, 2001, pp. 1-2
SBG	AL	Embedded Systems Programming, "Fundamentals of Firewire," obtained at website "http://www.embedded.com/1999.9906/9906feat2.htm," August 28, 2001, pp. 1-14

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8/21/03

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				FILING DATE January 25, 2002	
				GROUP ART UNIT 2812 2829	
SBG	AM	Microprocessor and Microcomputer Standards Committee of the IEEE Computer Society, "P1394a Draft Standard for a High Performance Serial Bus (Supplement)," The Institute of Electrical and Electronics Engineers, Inc., June 30, 1999, pp. T-27 43-67 <i>SBG 8/21/03</i>			
SBG	AN	Lucent Technologies, Inc., "IEEE 1394 Isolation," Application Note, November 1998, obtained at website "http://www.agere.com/1394/docs/AP98074-01.pdf," pp. 1-16			
EXAMINER <i>Atb. D.</i>			DATE CONSIDERED 8-21-03		
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TECHNICAL STAFF

10-1-03

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